

Product data sheet

NO CLEAN SOLDERING PASTE

easy print

/Sn96,5Ag3Cu0,5/

Description:

- Paste for soldering of surface-mounted (SMD) components

Advantages:

- Resistant to solderballing (mid chip solderballing)
- Good adhesion to components for over 24hrs after application
- Exhibits long stencil life even for 8hrs of continuous printing, prolonged usability (stencil life)
- Low level of colourless, non-corrosive soldering residues (no clean), that are flexible enough to allow penetration of tester needles
- Fine pitch
- Printing with squeegee speed up to 150mm/s

Technical details

Properties	Results	Procedures
Chemical		
type of solder	Sn96,5Ag3Cu0,5	
classification of flux	REL - 0	J-STD - 004
paper chromatography test on Clfiz	satisfy (REL - 0)	IPC TM 650
Physical		
density	≈ 4,6 g/cm ³	IPC-TM 650T
particle size	25-45 μm	IPC-TM 650T
tackiness	1,0 G/mm ² after 24h	IPC J-STD - 005
printability	more than 8h	
Electrical		
SIR-IPC	> 2,6*10 ⁹ Ω, after 7 days	IPC J-STD 004 (85° C, in 85%)

Symbols:

SIR - Surface Insulation Resistance

IPC - J STD 004/ 005, IPC - TM650 - American standards defining technical requirements for pastes and fluxes

easy print is a set of fluxes and activators that should be considered as non-toxic.

Application requirements

Storage	Printing	Reflow	Cleaning
<ul style="list-style-type: none"> ■ store in temp. 3-7 °C for no longer than 6 months in tightly closed containers. ■ the best (optimal) temperature of paste application: 23-26 °C ■ max. temperature of paste application: 28 °C ■ in order to avoid changes in rheology of the paste do not mix used with unused paste. ■ in order to prevent condensation of moisture and to achieve required properties of the paste warm the container up to room temperature for several hours before opening 	<ul style="list-style-type: none"> ■ laser-cut stencils or electro-formed stencils: ■ 100µm for pitch = 0.4mm ■ 150µm for pitch > 0.5 mm ■ metal stencils are recommended ■ squeegee travel speed in a printer: 25- 150 mm/sec ■ squeegee pressure: 1.5- 3N at a cm of length ■ amount of paste on a stencil: size of a roll rolling ahead of squeegee is 15-20mm 	<ul style="list-style-type: none"> ■ any soldering methods are allowed (air or nitrogen atmospheres) ■ preheating: ramp-up temperature 1- 2,0 °C/s to 145-160 °C or max. 210- 220 °C for versions without plateau ■ plateau phase (only for packages with high density assemblies having different mass) 145-160 °C for 60- 90s ■ soldering - reflow phase: 30-90s above 180 °C ■ cooling: gradient: 1-2 °C/s 	<ul style="list-style-type: none"> ■ as a rule a no-clean paste does not require cleanin ■ however if cleaning is necessary it is recommended to use alcohol PCB cleaner.